

02-10-2000

DEPARTMENT OF COMMERCE
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To the Honorable Commissioner of Patents and Trademarks
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Documents or copy thereof.

1. Name of conveying party(ies):
Donald J. Hayes

*MJD
1.19.00*

2100 JAN 19 AM 9:49

OPR/FINANCE

2. Name and address of receiving party(ies):

Name: MicroFab Technologies, Inc.

Internal Address: 1104 Summit Ave., Ste. 100

Street Address: _____

City: Plano State: TX ZIP: 75074

Additional name(s) of conveying party(ies) attached? Yes No

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other _____

Execution Date: January 12, 2000

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s)

09/004,392

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Harry J. Watson

Internal Address: Locke Liddell & Sapp, LLP

2200 Ross Ave., Ste. 2200

Street Address: _____

City: Dallas State: TX ZIP: 75201

6. Total number of applications and patents involved:

7. Total fee (37 CFR 3.41) \$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number: _____

(Attach duplicate copy of this page if paying by deposit account)

02/10/2000 DCDATES 00000027 09004392

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01 03:38 Statement and signature. 40.00 OP

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Harry J. Watson
Name of Person Signing

Harry J. Watson
Signature

January 12, 2000
Date

Total number of pages including cover sheet, attachments, and document:

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

For: U.S. Rights and Foreign Rights
For: U.S. Application
By: Inventor

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNOR:

Donald J. Hayes
2012 Tampico Drive
Plano, TX 75074

US
Nationality: US

hereby sells, assigns and transfers to

ASSIGNEE:

MicroFab Technologies, Inc.
1104 Summit Ave., Ste. 100
Plano, TX 75074
Nationality: US

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions and in all foreign countries, including all rights to claim priority, in and to any and all improvements which are disclosed in the invention entitled:

Method for Preparing A Chip Scale Package and Product Produced by the Method

and which is found in (37 C.F.R. section 3.21) U.S. application no. 09/004,392 filed on January 8, 1998 and any legal equivalent thereof in a foreign country, including the right to claim priority and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as

(Assignment)

may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent to which this verified statement is directed.

Date: 1-12-00



Signature of Donald J. Hayes

(Assignment)